DAY 2

COMPUTEX TAIPEI InnoVEX

JUNE 2 - 5, 2026

TaiNEX 1 & 2 | TWTC | TICC

# COMPUTEX DAILY






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COMPUTEX 2026 celebrated its grand opening on June 2.

# COMPUTEX 2026 Opens Amid Surging Global Demand for AI Infrastructure

COMPUTEX 2026 officially opened from June 2 to June 5 at Taipei Nangang Exhibition Center Halls 1 and 2, and Taipei World Trade Center Hall 1. Under the theme "AI Together," this year's show brings together 1,500 leading technology companies from 33 countries, occupying 6,000 booths, marking a record-breaking scale in the exhibition's history.

As artificial intelligence rapidly evolves from cloud-based computing into real-world deployment, COMPUTEX 2026 highlights the next wave of AI-driven industrial transformation and innovation. The exhibition reflects how global industries are accelerating toward intelligent infrastructure, physical AI applications, and connected ecosystems.

COMPUTEX 2026's opening day attracted an overflowing crowd of visitors.

Organized by TAITRA and the Taipei Computer Association (TCA), the opening ceremony was attended by President Lai Ching-te, Premier Cho Jung-tai, TAITRA Chairman James Huang, and TCA Chairman Jason Chen, who jointly inaugurated COMPUTEX 2026. Global technology leaders, international buyers, industry experts, and media representatives gathered in Taipei to explore AI technology trends and future business opportunities through exhibitions, forums, and networking activities.

President Lai highlighted, "The next phase of AI development will require trustworthy partners that share common values and are willing to work together globally. With its strong technological capabilities, comprehensive industrial ecosystem, and democratic system, Taiwan has become an important partner in the global AI landscape. Moving forward, Taiwan will continue to build a stable and reliable environment for innovation, and work with international partners to embrace the opportunities of the AI era."






President Lai Ching-te and TAITRA Chairman James C.F. Huang toured COMPUTEX 2026 with distinguished guests.

TAITRA Chairman James Huang added, "AI is ushering in a new chapter in human civilization. Under the theme 'AI Together,' COMPUTEX 2026 highlights how the future will be shaped through collaboration between people, AI, and industries worldwide. As a key hub of the global AI supply chain, Taiwan will continue to play a vital role in connecting innovation, technology, and international partnerships."

## Driving AI into Real-World Applications Across the Full Industry Chain

COMPUTEX 2026 focuses on AI computing, smart manufacturing, future mobility, next-generation communications, robotics, and sustainability technologies. New specialized zones: the AI Robotics Pavilion, Tech Application & Experience Zone, and E-Paper Pavilion, further expanding the show's AI ecosystem coverage from core chips and servers to platforms and end-user applications. By integrating hardware, software, platforms, and services, COMPUTEX demonstrates how AI technologies are rapidly moving into practical deployment while creating new business models through cross-industry collaboration.

Leading exhibitors include Acer, Adata, Advantech, ASRock, ASUS, Auras, BenQ, Chenbro, Delta Electronics, Gigabyte, Foxconn, Intel, MediaTek, MSI, MiTAC, and Pegatron, among others, jointly presenting the latest advancements in AI technologies and innovation achievements.

## InnoVEX Startup Zone Gathers Global Innovation Energy

As one of Asia's leading startup platforms, InnoVEX 2026 features nearly 500 startups from 23 countries, representing an 11% increase from last year. National pavilions from the Czech Republic, France, South Korea, Thailand, Australia, Japan, Canada, Israel, and Italy highlight growing international participation and cross-border innovation.

Global accelerators and startup ecosystems including NVIDIA Inception Program, Garage+, StarFab, and Interlink are also participating, connecting startups with investors, enterprises, and technology partners to foster collaboration and commercialization opportunities.

## Keynotes & Forum: Global Tech Leaders Gather in Taipei to Shape AI Future

This year's COMPUTEX Keynote features speeches from globally influential technology leaders, including Cristiano Amon, President and CEO of Qualcomm; Matt Murphy, Chairman and CEO of Marvell; Lip-Bu Tan, CEO of Intel; and Rafael Sotomayor, President and CEO of NXP Semiconductors.

The sessions focus on AI infrastructure, advanced computing, data centers, intelligent connectivity, and future technology trends, sharing the latest breakthroughs and industry insights.

The COMPUTEX Forum further explores AI industry applications and supply chain development, inviting global experts to discuss AI computing, smart manufacturing, robotics, sustainability, and emerging technologies, highlighting new opportunities in the AI era.

## Diverse On-site Programs Creating a Tech Lifestyle Ecosystem

In addition to the exhibition and forums, TAITRA has organized a series of activities including 1-on-1 sourcing meetings, guided tours, Sustainable Design Competition, and Pitch Contest to strengthen international business matchmaking and cross-industry collaboration.

This year also continues to host "Tech'em High" , connecting technology exchange with urban lifestyle experiences. In collaboration with China Airlines and fashion brand GQ, COMPUTEX has also created Service Lounge that combines business hospitality, lifestyle experiences, and relaxation spaces, further enhancing services for international exhibitors and visitors while demonstrating COMPUTEX's unique blend of technology professionalism and city charm, integrating technology exchange with urban lifestyle experiences.

COMPUTEX and InnoVEX 2026 run from June 2 to 5 at the TaiNEX 1 & 2, and Taipei World Trade Center Hall 1. Industry professionals are warmly invited to explore the latest breakthroughs in AI, experience cutting-edge technologies, and connect with global leaders shaping the future of innovation.

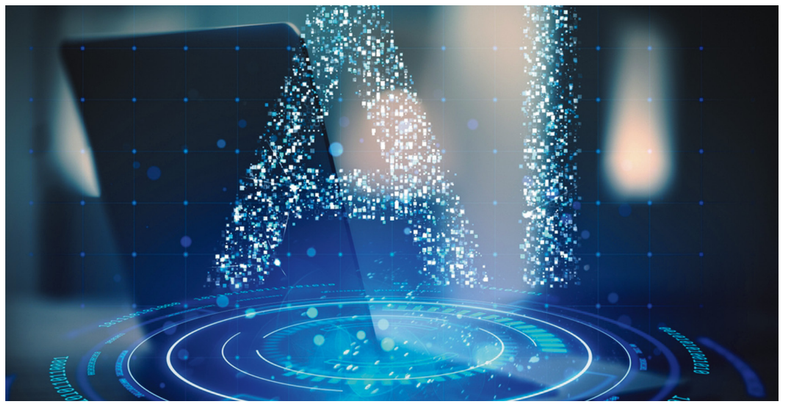
**For more information:**

- https://www.computextaipei.com.tw/en/index.html.
- www.innovex.com.tw

Official Website

Show Publications

# AI Ignites Global VC and Startup Boom: Energy and AI Emerge as Dual Engines for Propelling Taiwan's Innovations



Fueled by the generative AI (GenAI) boom, global VC has emerged from the shadow of the 2021 bubble burst, with worldwide funding now overwhelmingly concentrated on AI startups. This concentration of capital has reached a fever pitch, driven by technological breakthroughs in multimodal AI, agentic AI, and physical/embodied AI, alongside the widespread rollout of industry-specific AI applications.

## Global Tech Startup Landscape and VC Trends

Following the onset of the COVID-19 pandemic in 2020, governments and enterprises worldwide championed digital transformation, sparking an investment frenzy in cloud migration, SaaS, remote work, virtual meetings, mobile payments, e-commerce, and logistics systems. However, as overly bullish markets began to cool in 2021, the global VC sector experienced a market correction and bubble burst. This prompted a shift toward a more conservative and rational investment approach. Metrics such as business models, cash flows, and profitability became the new golden rules, while actual revenue and cost structures served as the primary benchmarks for determining target valuations.

PK Tseng, Senior Research Manager at TrendForce, has pointed out that OpenAI's launch of ChatGPT in 2022 reignited the market. Venture capitalists, who had previously grown cautious, began aggressively pouring capital back into the AI sector. As AI has emerged as the primary battleground for startups worldwide, the global VC landscape has undergone distinct structural changes.

## AI Startups Nearly Monopolize VC Funding

The most prominent trend today is that AI has undeniably become the core focus of global VC investment; present-day funding is almost entirely monopolized by AI startups. According to India's English-language daily newspaper The Economic Times, citing financial data and analysis firm PitchBook, over half of all global VC funding in 2025 has been absorbed by AI startups. In the US, a staggering 64% of VC funding has flowed into AI companies.

Data platform Crunchbase echoes this observation, reporting that AI investments account for 50% of total global funding in 2025 (reaching US$202.3 billion), a significant leap from 34% in 2024 (US$114.0 billion).

These funded startups span the entire AI technology stack. This includes AI foundation models (e.g., LLMs, multimodal AI, and world models), the AI application layer (e.g., AI coding, marketing, and healthcare), and AI infrastructure (e.g., AI chips, GPUaaS, AI data centers, and AI factories).

## Vertical, Sector-Specific AI Applications Begin to Flourish

"AI is going vertical" has become a popular catchphrase, with sectors such as healthcare, law, finance, manufacturing, logistics, real estate, and construction all developing industry-specific AI solutions. Not only are more AI startups emerging to focus on specific industry scenarios—such as medical diagnostics, insurance claims, ad generation, and factory optimization—but "vertical super apps" have also surfaced, catering to the unique needs of various industries better than general GenAI models.

According to a research report by market intelligence firm Market.us, the global vertical AI market is projected to reach approximately US$115.4 billion by 2034. This represents a massive surge from US$12.9 billion in 2024, reflecting a CAGR of 24.5%.

Taiwan is also influenced by this global trend. According to the "2025 Taiwan Startup Ecosystem Survey" jointly published by PwC Taiwan and the Taiwan Institute of Economic Research (TIER), an impressive 70% of local AI startups focus on vertical sectors. These startups primarily target industries with established data accumulation, such as marketing and advertising (32%), healthcare (30.4%), and logistics and transportation (19.3%).

## Capital Concentrates on Large Financing Rounds, Benefiting a Few Select AI Companies

According to observations by the World Intellectual Property Organization (WIPO), global venture capital is witnessing a phenomenon where total investment amounts are rising while the number of deals is declining. Consequently, with the increase in mega-rounds and a decline in smaller investments, capital is becoming highly concentrated, creating a one-sided, "winner-takes-all" dynamic.

AI startups not only absorb the vast majority of VC funding, but the scale of each AI funding round is also trending larger. Mega-rounds exceeding US$500 million to US$1 billion have become commonplace in the AI sector.





## Tech Giants Ramp Up Startup Investments, Boosting the Influence of CVC

Tseng stated that a growing number of tech giants and major global enterprises—including NVIDIA, Microsoft, Amazon, and Google—are investing heavily in AI and industry startups. These investments are driven by strategic goals, such as building specialized ecosystems, acquiring cutting-edge technologies, and laying the groundwork for future M&As. This trend has elevated the influence of corporate venture capital (CVC) to an all-time high.

When it comes to AI startup investments, NVIDIA, Microsoft, and Amazon have all made big moves. For instance, both Microsoft and NVIDIA have invested in OpenAI. Microsoft alone has poured tens of billions of dollars into the startup, deeply integrating its technology into Azure and Copilot. Meanwhile, NVIDIA leverages its investments to anchor its AI ecosystem, forging a symbiotic relationship with computing power and model developers. Additionally, Amazon has invested billions of dollars into Anthropic, closely tying the startup to its AWS platform.

Tech giants have made even more extensive investments across other industries. Please refer to the accompanying table for detailed investment cases.

## ESG and Sustainability Drive a Boom in Climate and Energy Tech Startups

Driven by net-zero emission policies, surging AI-related power consumption, and energy security concerns, energy and climate technologies have emerged as the next major battleground for startups. Today, energy startups are primarily concentrated in areas such as advanced batteries, hydrogen energy, nuclear fusion, carbon capture, power grid technologies, and energy solutions for AI data centers.

This trend is particularly pronounced in Taiwan. According to the "2025 Taiwan Startup Ecosystem Report" by business acceleration platform Dream Rich, Taiwan now boasts 10,028 startups. Energy and sustainability companies make up the largest share. This sector is also the top priority for the island's corporate venture capital (CVC). It leads the CVC investment "iron triangle" by capturing 20.30% of investor focus, followed by healthcare (13.37%) and hardware (13.14%).

## Tech Startup Landscape and VC Trends in Asia and Taiwan

Startup funding in Asia is primarily concentrated in a few key countries: China, India, Singapore, Israel, Japan, and South Korea. These markets are defined by their massive scale, rapid growth, and strong government support. While Taiwan's startup ecosystem is relatively small by comparison, it boasts unparalleled advantages in sectors such as semiconductors, ICT hardware, the IoT, and deep tech.

Compared to Silicon Valley venture capitalists—who often chase high-risk, high-growth opportunities—Asian investors tend to be more conservative. They focus heavily on revenue generation, viable business models, and clear timelines to profitability.

According to KPMG's "Venture Pulse Q1 2025" report, VC investments in Asia plummeted to US$12.93 billion in the first quarter of last year—its lowest level since 2015. This decline was largely attributed to a lack of landmark, large-scale funding deals.

In contrast, Taiwan's startup investment landscape presents a different picture. According to the "2025 Taiwan Startup Ecosystem Report" by Dream Rich, total funding reached a record high of US$3.34 billion across 605 deals in 2024. From 2015 through the first quarter of 2025, cumulative startup investments in Taiwan hit US$18.95 billion.

The report categorizes Taiwan's AI startup investments from 2015 through the first half of 2025 into three major areas: AI infrastructure, cross-industry applications, and vertical industry applications. Vertical AI emerged as the hottest segment, attracting US$1.036 billion. This was followed by cross-industry AI applications (US$633 million) and AI infrastructure (US$452 million). These figures highlight how Taiwan is actively leveraging its ICT strengths to implement tangible AI solutions across diverse industries.

**Overview of Tech Giants' Investments in Startups Across Various Industries**

| Tech Giant | Sector | Sub-Sector | Startup |
|---|---|---|---|
| Alphabet GV | Energy technology | Geothermal | Fervo Energy |
| | Biotechnology | DNA genetic testing | 23andMe |
| | Medical technology | Cancer data platform | Flatiron Health |
| | Financial technology | Payment infrastructure | Stripe |
| | Deep technology | 3D printing digital manufacturing | Carbon |
| | Direct-to-consumer retail | Eyewear brand | Warby Parker |
| | Direct-to-consumer retail | Beauty brand | Glossier |
| Microsoft | Climate technology | Direct air capture carbon removal | Climeworks |
| | Climate technology | Mineralization carbon capture | Heirloom |
| | Mobility technology | Autonomous vehicles | Cruise |
| | E-commerce and logistics | Digital freight | Flexport |
| Amazon | Energy technology | Green fuel | Infinium |
| | Climate technology | Concrete carbon utilization | CarbonCure |
| | Medical technology | Healthcare | One Medical (Acquired) |
| | Medical technology | Digital musculoskeletal care | Hinge Health |
| | Mobility technology | Electric vehicles | Rivian |
| | E-commerce and logistics | Delivery platform | Deliveroo |
| | E-commerce and logistics | Digital freight | Convoy |
| | E-commerce and logistics | Autonomous trucks | Aurora Innovation |

(Source: Compiled by TechNews)

## From Follower to Pioneer: A Golden Decade for Taiwan's Startups

As AI transitions from virtual algorithms to physical and vertical applications, Taiwan is capitalizing on its deep semiconductor roots and manufacturing prowess. The island is evolving from a mere participant in the global supply chain into a driver of both AI innovations and the energy transition.

Tseng believes the biggest advantage for startups in Taiwan is combining hardware and software. The island is building strong competitive advantages in challenging sectors like sustainable energy, smart manufacturing, and defense tech. This sets the stage for a golden decade. Taiwan will no longer just participate in the AI boom. Instead, the island's startups will be shaping the future of smart living.

(Header image source: Shutterstock.)

# Marvell, NVIDIA Tout Connectivity and Optics as Next Frontier for AI Infrastructure

Matt Murphy, Chairman and CEO, Marvell

Matt Murphy, Chairman and CEO of Marvell Technology, and Jensen Huang, founder and CEO of NVIDIA, on June 2 discussed how their companies are collaborating to provide customers with greater choice and flexibility in developing next-generation artificial intelligence (AI) infrastructure at the Taipei Nangang Exhibition Center Hall 2.

Murphy noted that tens of thousands—and eventually millions—of computer processors must work together as a single, massive compute engine, making computing at this scale fundamentally a connectivity challenge —- the next major wave of innovation and scale.

Citing tech giants Meta, Google, AWS, and Microsoft, Murphy said the industry was undergoing a major transformation. Just as it did with compute and memory, the tech sector would rally to meet this connectivity challenge, he said.

As reasoning models, mixture-of-experts architectures, and generative AI continue to evolve, larger volumes of data must move across infrastructures, demanding higher bandwidth and lower latency. Because workloads could no longer fit into a single data center, larger facilities must be built, Murphy said.

Consequently, connectivity had become a critical enabler of scaling compute, with optics widely recognized as the path forward, he said.

Highlighting a recent expansion of Marvell's partnership with Nvidia—supported by a US$2 billion investment from the latter—Murphy said the two companies are broadening their collaboration across multiple dimensions, including optics, photonics, and NVLink Fusion.

Huang, who appeared as Murphy's special guest, noted that AI agents utilize a highly disaggregated and distributed computing pattern, making robust connectivity essential.

When asked about the transition from copper to optics, Huang said that while copper faces limitations in bandwidth and distance, the ultimate strategy is to scale up with copper, scale up and scale out with optics, and eventually scale across using optics.

The intersection of the two technologies would persist for a long time, Huang said, predicting that the industry would use "a ton of copper and tons of optics" over the next five to ten years as data centers become core infrastructure.

During the keynote, Murphy presented Marvell's latest optical module and announced the new T100 Ethernet Switch, which is specifically designed for AI data centers and features the industry's lowest power consumption.

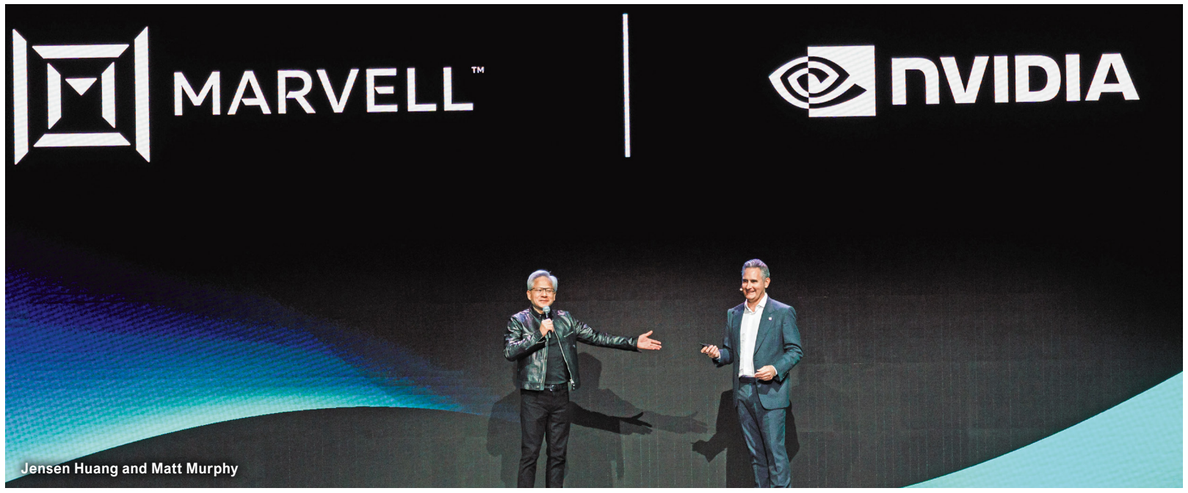
He also introduced co-packaged optics (CPO) as a solution to the fundamental challenges of density and power, calling the technology a massive shift for the industry.

Despite its high complexity, CPO is the only way to continue scaling bandwidth and overcome current hardware limitations while simultaneously reducing power consumption, Murphy said.

"This is happening now," Murphy said. "This is where the industry is heading."

The AI infrastructure industry is moving toward a future of "data center without distance," where compute, memory, networking and photonics operate as one unified system, and where millions of resources across the data center can work together as if they were one machine, he said.

This would be an architecture defined by the needs of the workload, not by the limits of the connectivity, he said, "We believe this is the next era of computing infrastructure."




Jensen Huang and Matt Murphy





# From PCs to Data Centers: How Intel is Powering the Shift to Agentic AI

The transition to agentic AI would demand computing upgrades from personal devices to data centers, with Intel's silicon powering this next wave of AI workloads, Intel CEO Lip-Bu Tan said during his keynote at COMPUTEX 2026 on June 2. Intel is orchestrating these silicon upgrades across PCs, edge devices with agentic or physical AI, data centers and intelligent centers, Tan said at the Nangang Exhibition Center Hall 2 in Taipei.

Lip-Bu Tan, CEO
Intel

Alex Katouzian, Executive Vice President and General Manager of Intel's Client Computing and Physical Group AI, highlighted the progress across PCs. The Intel Core Ultra Series 3 introduced in April can "transform any PC into an agentic capable platform," Katouzian said, emphasizing that it is already being used in more than 70 light, thin laptops designed by Intel's partners. Katouzian noted Intel's silicon would enable customers to expand into new physical AI, which is projected to be a US$25 trillion market by 2050.

Perplexity Co-Founder and CEO Aravind Srinivas demonstrated a hybrid agentic AI system running on a laptop. Srinivas showed how this hybrid system runs smaller AI models locally on the Intel Core Series 3, while outsourcing other computing to the data center to maximize efficiency and ensure privacy.

Shifting to infrastructure, Kevork Kechichian, Executive Vice President and General Manager of Intel's Data Center Group, discussed the silicon transformation happening in data and intelligence centers. AI inference workloads are expected to become 40% of all data center power demand, Kechichian said. "For agentic AI, the CPU orchestrates the show," he said, introducing how the Intel Xeon 6+, unveiled at COMPUTEX yesterday, can power this shift. While generative AI placed more demand on GPUs, agentic AI workloads are much more CPU intensive. Intel is working with partners to design server racks that meet these unique enterprise needs, Tan added.

Tan explained that agentic AI is causing token usage to explode, making it critical to design compute solutions optimized for token consumption. SambaNova Co-Founder and CEO Rodrigo Liang introduced the SambaRack SN50, which uses Intel's CPUs, Nvidia's GPUs and SambaNova's RDUs to orchestrate disaggregated inference. The SN50 is two to three times faster than a pure GPU stack, Liang said.

Vista Equity Partners CEO Robert Smith highlighted that the shift toward agentic AI is driving immense demand for computing and reshaping silicon software. Through its partnership with Intel, Vista is introducing the first commercially available architecture for disaggregated inference to turn existing data centers into efficient, air-cooled inference hubs, Smith said.

Tan closed with examples of how Intel's custom silicon solutions can support all kinds of companies in meeting their goals, highlighting partnerships in biomedical engineering with Echo, biomedicine with Greenstone, energy with Hitachi and industrial automation with Siemens.

# Robotics: "the Single Largest Opportunity in Front of Humanity"

## The “Robotics, Autonomous Machines & Physical AI” forum at COMPUTEX 2026 featured NVIDIA, Qualcomm, ABB Robotics, NXP — and a full-sized, walking humanoid robot

Robots are “the single largest opportunity in front of humanity,” Deepu Talla, Vice President of Robotics and Edge AI at NVIDIA, said in his opening remarks at Tuesday's forum on Robotics, Autonomous Machines and Physical AI.

The first forum of COMPUTEX 2026 showcased humanoid robots and the latest developments from NVIDIA, Qualcomm, ABB Robotics and NXP.

At last year’s forum, Talla described how “the future was coming to the present,” and this year, the future is here.

The latest developments in physical and agentic AI are now bringing embodied AI into our stores, factories and, soon, our homes.

AI-powered robotics are being deployed across Taiwan, “the land of manufacturing,” led by industry leaders from Foxconn to TSMC, Talla said.

The robotics industry is now poised for rapid expansion. With fewer than one million robots in use today, the future could see billions, or even tens of billions, across every sector, Talla said.

Talla was even willing to bet that, in the next one or two years, every person in attendance would work with robotics in some capacity.

But NVIDIA doesn’t build robots — it powers them through platforms and workflows for robot training, programming, and simulation at an industrial scale.

With their latest model, the NVIDIA Isaac GROOT Robotics Development Platform, “what would take nine months to a year would now take less than a day,” Talla said.

Nakul Duggal of Qualcomm, up next, brought a full-sized humanoid robot on stage, demonstrating real-world potential, and more importantly, to present on a silver tray the latest Qualcomm release: the Dragonwing IQ10 Robotics Reference Design (RRD).

The system integrates hardware, software and AI tools into a single deployment-ready robotics platform.

Echoing Talla’s robo-optimism, Duggal said, “We have never lived in a world that has this incredible amount of change in front of us.”

In the next presentation, Craig McDonnell of ABB Robotics introduced the company’s latest developments, following five decades of innovation.

Since ABB pioneered the world's first commercial all-electric microprocessor-controlled robot back in 1974, today it makes more than 1,000 robot varieties.

Nakul Duggal, EVP and Group GM, Automotive, Industrial and Embedded IoT, and Robotics Qualcomm

The company is now developing intelligent eyes, hands and brains to power more autonomous and versatile robots, he said.

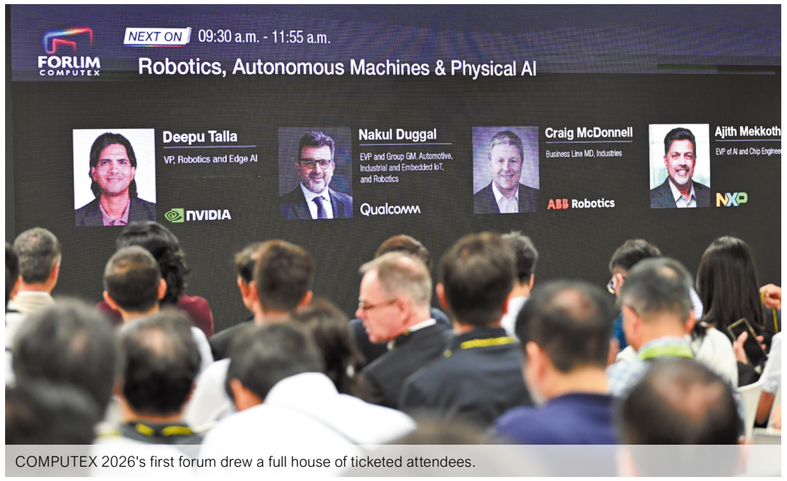
ABB Robotics partnered with NVIDIA in March to bring physical AI capabilities to the factory floor. By generating hyperrealistic synthetic data, manufacturers can close the "sim-to-real" gap and achieve up to 99 percent accuracy between virtual and real-world environments, helping robots adapt more effectively to changing conditions.

The market is seeing “exploding complexity perhaps not anywhere near the same level as just five years ago,” McDonnell said, as technologies require faster development and manufacturing expands beyond China into Vietnam, India and, hopefully, North America.

Lastly, Ajith Mekkoth of NXP introduced how edge AI can be applied across thousands of real-use cases, from neonatal monitoring machines in hospitals to at-home assistive robot arms.

NXP focuses on scalable, sustainable robotics systems with manageable compute costs and upgradeable designs, he said.

“We are at the precipice of ubiquitous AI,” he said, as robotics moves from experimentation to real-world deployment at scale.



COMPUTEX 2026's first forum drew a full house of ticketed attendees.





# Innovative Applications of AI, Robotics and Edge Computing in Manufacturing and Service Industries

At COMPUTEX 2026's Taipei World Trade Center (TWTC) venue, the Robotics zone and the ePaper Pavilion host over a thousand booths, where exhibitors showcase robots, AI, and edge-computing applications designed to advance manufacturing and the service sector — while ensuring that emerging technologies remain environmentally sustainable.


COMPUTEX 2026's Robotics zone at TWTC Hall 1 is the show's biggest draw this year.

First and foremost on the list was Eink, a company specializing in Electrophoretic Ink technology, or digital ink, that recreates the effect of ink on paper on display media. In addition to its traditional products, such as e-ink books and paintings, E Ink has collaborated with BMW this year to showcase its color-changing e-paper technology, the E Ink Prism, which, for the first time, can conform to the contours of 3D surfaces.

The e-paper, rolled into thin films, is applied to the BMW iX3 Flow as one would apply car tint films and could work with the built-in AI systems and the sensors in the car to shift colors due to intent, such as changing the color of the door when the driver is about to step out. In the future, the company also intends for the sensors to gauge driver fatigue and adjust the car’s exterior colors accordingly.

Another booth of note at the pavilion was Vyin AI, which has stated its intent to explore the applications of AI and robotics in the tertiary industry, marking a departure from current trends toward maximizing AI use on the manufacturing floor.

The BMW iX3 Flow displays E Ink's color-changing Prism e-paper at the E Ink x BMW booth, COMPUTEX 2026.

Solomon Technology displays robotic arms powered by its recognition-and-scanning vision technology at COMPUTEX 2026.

Showcasing a wide range of robotics applications, the Robotics & Edge AI Pavilion stands out as the biggest highlight of COMPUTEX 2026.

The company proposes to use AI in tandem with robotics in the pharmacy and retail markets, namely as a service and sales agent. In pharmacies, Vyin AI said it recognized that legal constraints prohibit promoting drug use and has set stringent parameters for AI to follow when queried about which drugs to use. In the latter, robots would be able to lead customers to desired product locations upon query.

Solomon Technology Corp, brought to COMPUTEX 2026, robo-arms and other systems that pair with its core tech focus - recognition and scanning. The company provides solutions and products that help manufacturers verify whether product assembly went according to plan, and also offers services that walk engineers through the steps of quality checking products.

Advantech has brought to the floor its specialized solutions and products for Edge AI and Internet of Things (IoT), and provides the necessary engines and systems to facilitate and accelerate real-world AI adoption.

Of note is also the HipBo from Free Bionics, an example of AI tech making its foray into medicine. The exoskeleton helps those in rehabilitation by detecting the user’s movement intent and enabling high-intensity, repetitive movements to re-establish neural connections, while also greatly reducing the number of medical staff required to assist with transfers from a wheelchair or bed into the device.

# NVIDIA Vera Rubin NVL72 Awarded the Best Choice of the Year

Asia's leading B2B ICT trade show, COMPUTEX TAIPEI is officially stared today (the 2ndnd) at Taipei Nangang Exhibition Center Halls 1 & 2 and TWTC Hall 1. As one of the organizers, Taipei Computer Association (TCA) stated that COMPUTEX serves as a major platform for global buyers and media attention. During today's opening ceremony, the official award of the event—Best Choice Award (BC Award)—proudly announced its top honor, the Best Choice of the Year, which was awarded to NVIDIA Vera Rubin NVL72.


Making BC history as the first-ever product to sweep three major awards, the NVIDIA Vera Rubin NVL72 redefines rack-scale AI supercomputing. Integrating 72 Rubin GPUs and 36 Vera CPUs via 6th-generation NVLink technology, this platform acts as a single, unified system optimized for trillion-parameter models. The architecture features a revolutionary cable-free, hose-free, and fanless design. Armed with a 100% liquid-cooled architecture that supports 45°C water to save up to 60MW in large AI factories, it delivers a generational leap of 10x higher performance-per-watt—slashing inference costs per token while achieving ambitious energy-saving targets and peak operational sustainability. As a result, it was awarded the Best Choice of the Year, Golden Award and Sustainable Tech Special Award.

The winning products of BC Award this year span across various technological fields, including AI Compute, AI Application, Gaming, Robotics and Environmental Sustainability, fully aligning with the procurement trend of international buyers.

Best Choice Award 2026 demonstrates the innovative momentum and commitment to sustainability of the technology industry. To enhance the award's visibility and attract greater attention from both domestic and international buyers, all winning products will be displayed during COMPUTEX TAIPEI (Booth No. R1214a), inviting global industry professionals to join us in witnessing the energy of technological transformation and green future.

For detailed information and judges' comments for all winning products, please check official Best Choice Award website.

https://bcaward.computex.biz/

## Best Choice of the Year Award

| Awarded Product | Company |
|---|---|
| NVIDIA Vera Rubin NVL72 | NVIDIA |

## Golden Award

| Awarded Product | Company |
|---|---|
| 800VDC 2.4MW Liquid-to-Liquid Coolant Distribution Unit (CDU) | Delta |
| AI Containerized Data Center | Delta |
| AI-Ready, Single-chip Wi-Fi 8 tri-band connectivity chip with UHR+ | MediaTek |
| Drone image processing and AI object detection and tracking | ELAN |
| Edge AI Multi-Port High-Speed Switch IC | ASMedia |
| Integrated Ethernet Switch | Realtek |
| Intel® Core™ Ultra Series 3 processor | Intel |
| MSI GeForce RTX™ 5090 32G LIGHTNING Z | MSI |
| NVIDIA Jetson Thor | NVIDIA |
| NVIDIA Vera Rubin NVL72 | NVIDIA |
| PASCARI D206V: 245TB Ultra-High Capacity Enterprise SSD | Phison |
| ROG G1000 Edition 20 | ASUS |

## Sustainable Tech Special Award

| Awarded Product | Company |
|---|---|
| AecoPost Color ePaper Solution | AUO |
| AI Containerized Data Center | Delta |
| ASUS ExpertBook Ultra | ASUS |
| Mobile Medical AI Workstation on Wheel | Wincomm |
| NVIDIA Vera Rubin NVL72 | NVIDIA |
| SHARP ePoster Electronic Paper Display, EP-CA22 | SHARP |
| XPG NOVAKEY RGB DDR5 Gaming Memory | ADATA |

## Category Award

| Awarded Product | Company |
|---|---|
| "Acer Medical" VeriSee GLC | Acer |
| 3D Facial Recognition Module | Kneron |
| 6.7 mm Smaller Footprint e.MMC | ATP |
| aiDAPTIV™ AI PC Turbo-Inference Solution | Phison |
| AirJet Mini G2 | Frore Systems |
| AK700ST \| 4K Laser Short-Throw Golf Simulator Projector | BenQ |
| AORUS MASTER 16 | GIGABYTE |
| AORUS RTX 5090 AI BOX | GIGABYTE |
| ASUS Ascent GX10 | ASUS |
| ASUS Zenbook DUO (UX8407) | ASUS |
| BOXER-8629AI \| IP67 Waterproof Fanless Embedded Edge AI System | AAEON |
| Chessnut Move Automated Chessboard | Xenx |
| Compact Edge AI Platform Powered by NVIDIA® Jetson Thor™ | ADLINK |
| Copilot Key–Integrated AI Intelligent Fingerprint Authentication and High-Precision Cursor Navigation Control | ELAN |
| E Ink Spectra 6 ePaper Signage System | E Ink |
| Edge AI Accelerator | Realtek |
| Edge AI Inference System | Advantech |
| EXPERT P35S External SSD (One-Click Data Destruction) | Team Group |
| High Heat Exchange Efficiency Cooling Distribution Units | Auras |
| High-Efficiency AI-Driven Wi-Fi 8 Tri-Band Flagship Router | MediaTek |
| j-mex Digital Twin & Teleoperation Engine | J-MEX |
| MPG Ai TS series | MSI |
| NVIDIA Alpamayo | NVIDIA |
| PCIe to Multi-IO Bridge Controller | Realtek |
| PEGAVERSE YODA | PEGATRON |
| Predator XB273K 3D Gaming Display | Acer |
| ProArt GoPro Edition (PX13) | ASUS |
| ROG Cetra Open Wireless | ASUS |
| ROG Flow Z13-KJP (2026) | ASUS |
| ROG Rapture GT-BN98 Pro | ASUS |
| ROG Zephyrus Duo (2026) | ASUS |
| ROG Thor 3000W Titanium III Edition 20 | ASUS |
| SIMATIC Robot Pick AI Pro | Siemens |
| STRIKE ALLOY TMR & STRIKE NEXUS | MSI |
| Titan 18 HX Dragon Edition Draco Epic | MSI |
| TRUSTA AI Scaler Extended Memory Solution | ADATA |
| X870E AORUS XTREME X3D AI TOP | GIGABYTE |

## SME Special Award

| Awarded Product | Company |
|---|---|
| AI Surveillance Station | PLANET |
| Cloud-Edge VLM Enabled AMR Platform | eYs3D |



# Redefining the Future of Industry: 10 Japanese Innovators Showcasing AI, Deep Tech, and Mobility at InnoVEX 2026

Curated delegation of ten cutting-edge Japanese companies is set to arrive at InnoVEX 2026, bringing a powerhouse of solutions designed to tackle the most pressing challenges in the modern business landscape. From AI-driven operational optimization to world-class thermal management and next-gen mobility, this pavilion offers a unique window into the future of Japanese technology. Whether you are a distributor seeking the next market-ready product or a strategic leader looking for a co-innovation partner, these innovators are ready to accelerate your business to the next stage.


### AI-Driven Transformation: Mastering Complexity

Actionable intelligence at scale. Move beyond the hype and see how complex data transforms into decisive, real-world results. From automating mission-critical planning to industrial-grade voice AI and unified marketing decision-making, witness the intersection of intelligent automation and operational excellence. These are the solutions built to eliminate uncertainty and fuel a scalable growth engine for the next wave of transformation.

### Hardware × Technology: Powering the Physical World

Step into the edge of what's possible. Experience the physical breakthroughs defining the AI and urban eras. Highlights include innovative thermal dissipation technology that utilizes specialized fillers on surface interfaces to drastically enhance cooling efficiency for AI GPUs, alongside next-gen urban mobility solutions. The companies also feature high-performance AI Vision Processors with integrated tamper-proof engines for secure surveillance. Bridging these to the Japanese market is the strategic B2B gateway, connecting global innovators with quality leads and executive access. Here, the physical building blocks of the next industrial revolution meet the strategic roadmap for success.

### Human × Technology: Unlocking Human Potential

Empowerment through insight. Where technology bridges the gap between human intuition and digital precision, new possibilities for growth emerge. Discover AI-powered visualization of internal states using biometric data, alongside platforms empowering high-end careers through the power of human and technology and digital business card ecosystems that transform professional networking. These innovators are redefining how organizations connect, communicate, and manage their most valuable asset: people.

## Exhibitor List

- SORABITO INC.
- ALGO ARTIS CORPORATION
- REHATCH INC.
- KATO LIGHT METAL INDUSTRY
- DMP INC. / STARBIT
- LEAN MOBILITY INC.
- EVERIDGE CO., LTD.
- OLIVE CORP.
- ASSIGN INC.
- SHARE-ME

JAPAN
Bizcrew Pavilion

**Visit booth S0118, Japan Bizcrew Pavilion in the InnoVEX to experience the core of Japanese innovation firsthand.**

### EVERIDGE CO., LTD.

- www.everidge.co.jp/company/ja
- **S0118** | TaiNEX 2





# Open Source Team Taiwan: From Hardware Strength to Full-Stack AI Innovation


Open Source Team Taiwan Pavilion has officially debuted at COMPUTEX 2026, launched by distinguished guests from industry, government, academia, and research, witnessing the unveiling of Taiwan's open-source AI ecosystem

At COMPUTEX TAIPEI 2026, Open Source Team Taiwan presents a first-of-its-kind pavilion showcasing Taiwan's growing open source capabilities in the AI era. Supported by the Administration for Digital Industries (ADI) and organized by the Information Management Association (IMA), the pavilion is not just a showcase of individual projects — it is a gateway to Taiwan's emerging open source AI ecosystem, where software startups, hardware leaders, research communities, and global contributors come together.

The pavilion features 15 selected projects across four major categories: Software-led OSS Business, highlighting software companies and startups turning open source into real business models; Hardware-led OSS Innovation, showcasing how the hardware and semiconductor ecosystem is expanding into open software and AI infrastructure; Community & Academic OSS, presenting projects initiated by research institutions and open source communities; and Taiwanese Footprints in World-Class OSS, highlighting local contributors behind globally important open source projects.

Together, these projects form a full-stack view of Taiwan's open source AI ecosystem across five layers:

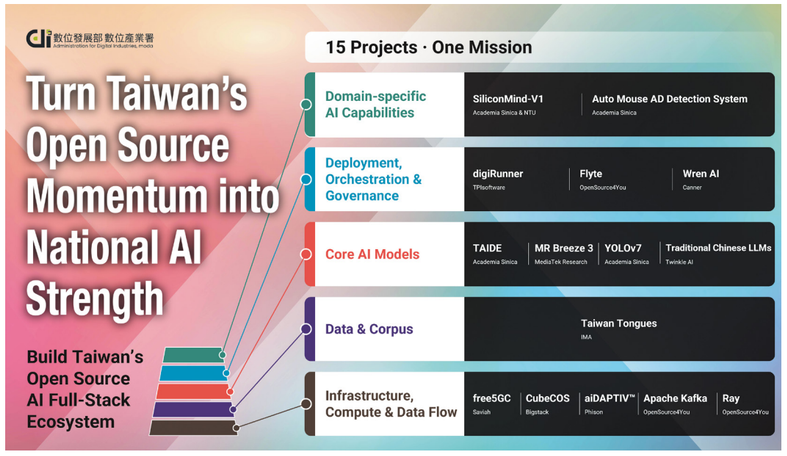
- Infrastructure, Compute & Data Flow: free5GC, CubeCOS, aiDAPTIV™, Apache Kafka, and Ray demonstrate Taiwan's capabilities in connectivity, cloud infrastructure, hybrid AI computing, real-time data streaming, and distributed ML workloads.
- Data & Corpus: Taiwan Tongues brings Taiwan's local language, cultural context, and linguistic diversity into AI development, creating a stronger foundation for localized and trustworthy AI.
- Core AI Models: TAIDE, Breeze 3, YOLOv7, and Traditional Chinese LLMs show Taiwan's progress in trusted language models, Taiwanese speech recognition, AI safety guardrails, computer vision, and Traditional Chinese AI development.
- Deployment, Orchestration & Governance: digiRunner, Flyte, and Wren AI support enterprise AI adoption through API management, workflow orchestration, governance, and business intelligence.
- Domain-specific AI Capabilities: SiliconMind-V1 and the Auto Mouse AD Detection System demonstrate how open source AI can be adapted to specialized domains, including IC design and biomedical research.

Beyond the exhibition, Open Source Team Taiwan will host a series of events to connect global visitors with Taiwan's ecosystem. On June 3 at 13:00, two internationally recognized open source leaders — Brian Behlendorf (Board Member of the Electronic Frontier Foundation and former General Manager of the Open Source Security Foundation), and Justin Mclean (ASF Board Member and Community Manager at Datastrato) — will speak at the InnoVEX Center Stage under the theme "Open Source Strategy: From Trust to Business." Later the same day, at 15:00, an off-site meetup at Taipei New Horizon will bring together startups, engineers, software companies, and open source communities for deeper dialogue and networking.

With "Open. Contribute. Lead." as its call to action, the pavilion invites enterprises, startups, investors, and developers to discover how Taiwan is building with open source, contributing to global ecosystems, and turning open collaboration into AI-era industrial competitiveness.

### OPEN-SOURCE TEAM TAIWAN

- reurl.cc/aXgkDX
- **S0524** | TaiNEX 2



ADVANTECH

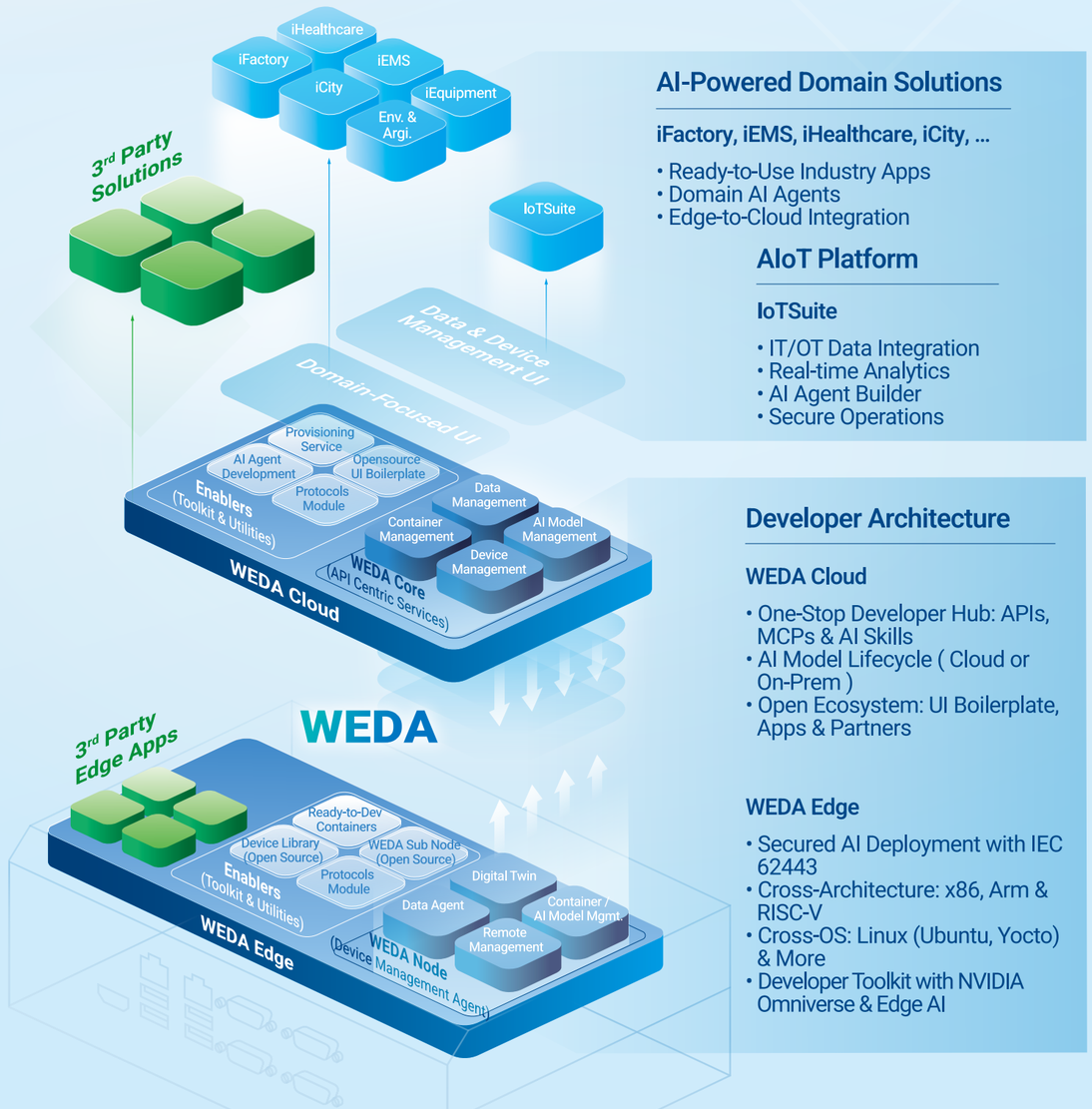
*Enabling an Intelligent Planet*

***Edge Computing & AI-Powered WISE Solutions***


# Realizing Next-Gen Edge AI Applications with WEDA

**WEDA** is an **AI-first developer architecture** that transforms industrial hardware into a programmable Edge AI platform. It enables AI agents to directly interact with devices via standardized APIs, containers, and digital twin integration—simplifying development, accelerating deployment, and unlocking scalable, intelligent operations across edge-to-cloud environments.

Visit Advantech Booth at COMPUTEX




## AI-Powered Domain Solutions

**iFactory, iEMS, iHealthcare, iCity, ...**

- Ready-to-Use Industry Apps
- Domain AI Agents
- Edge-to-Cloud Integration

## AIoT Platform

**IoTSuite**

- IT/OT Data Integration
- Real-time Analytics
- AI Agent Builder
- Secure Operations

## Developer Architecture

**WEDA Cloud**

- One-Stop Developer Hub: APIs, MCPs & AI Skills
- AI Model Lifecycle ( Cloud or On-Prem )
- Open Ecosystem: UI Boilerplate, Apps & Partners

**WEDA Edge**

- Secured AI Deployment with IEC 62443
- Cross-Architecture: x86, Arm & RISC-V
- Cross-OS: Linux (Ubuntu, Yocto) & More
- Developer Toolkit with NVIDIA Omniverse & Edge AI

# BXB's AI Integration & Wireless Freedom: Reshaping Communication Scenarios

Under the new normal of hybrid work and smart education, communication devices are no longer just audio tools—they are the "brains" of spatial collaboration. BXB's flagship products solve the pain points of cumbersome wiring and rigid layouts found in traditional systems through the integration of AI and DECT wireless technology.

A major highlight is the newly launched wireless mic—the ADM-2000 Series, alongside the 2026 iF Design Award-winning T-Flex Wireless Conference Mic. BXB's wireless mic series exclusively utilizes the DECT 1.9GHz band, bypassing crowded 2.4GHz Wi-Fi interference and eliminating the frequency-tuning hassles and management nightmares of traditional UHF and infrared mics. They also feature AES-256 military-grade encryption to ensure every meeting is strictly eavesdrop-proof.

The ADM-2000 Series delivers an ultra-lightweight, plug-and-play experience with pristine audio quality, freeing speakers from cable constraints.

**Featherlight Design:** Weighing only 37g, it is as compact as a flash drive and practically weightless when worn.

**Up to 1-to-32 System:** Registers up to 32 mics with 8 speaking simultaneously, perfectly adapting to multi-person collaborative scenarios.

**Plug-and-Play:** The ADM-2000 Mini portable model is designed for personal use. With zero waiting and no pairing required, presenters simply walk into the classroom with the receiver, plug it into a 3.5mm or USB-C port, and instantly start speaking—achieving the ultimate "walk and talk" freedom.

The 2026 iF Design Award-winning T-Flex Wireless Conference Mic seamlessly integrates the world's first "Magnetic Quick-Release" design for instant desktop-to-handheld switching. Users are no longer confined to their seats, maintaining professional audio quality whether speaking from a fixed point or delivering a roaming presentation. Combined with BXB's exclusive "AI Auto-Tracking" technology, it accurately auto-captures close-ups of the active speaker without manual backend operations. This intuitive "audio-visual sync" experience significantly lowers communication costs in hybrid meetings, providing remote participants with an immersive sense of presence.

**BXB ELECTRONICS CO., LTD.**

- www.bxbsystem.com
- **K1321a** | TaiNEX 1

## Wireless Audio

Go Far. Speak Freely.

DESIGN AWARD 2026

**World's First Magnetic Quick-Release Conference Mic**

Transform desktop into handheld mold in 1 second

## AI-Powered

Talk and Track

**Zero-Setup AI Tracking:** Press the talk button to instantly preset the mic position and auto-center the speaker. No manual presets needed.

**AR Spatial Canvas:** Frequent room changes? Simply align furniture with our "on-screen virtual bounding boxes" software for 100% precise layout restoration.

BXB

**The Expert in Smart Meeting and Educational Spaces**

# Datotek Unveils ARES AEROFIN: Ultra-Slim 1cm PCIe Gen5x4 Active SSD Cooling Module for PS5 and PC

## Premier PS5 SSD Cooler Prevents Thermal Throttling, Optimizing Gaming Performance

Datotek launches the ARES AEROFIN, an ultra-slim 1cm PCIe Gen5x4 active SSD cooling module designed for PS5 consoles and high-end PCs. The solution features a high-density skived-fin heatsink with a 5V micro fan, reducing peak SSD temperatures by up to 40%—from 91.4°C to 42.6°C—while sustaining speeds of 14,000MB/s without thermal throttling. Gamers can maintain consistent performance during extended play sessions, making it ideal for competitive setups.

Built for next-generation gaming, the 20g lightweight AEROFIN fits PS5 M.2 2280 slots, laptops, and standard motherboards without GPU interference. Its compact design ensures compatibility with PS5 SSD expansions and PCIe Gen5 platforms. The active cooling system improves efficiency by directing airflow across the heatsink, supporting AAA gaming, ray tracing, and AI-driven workloads.


Compared to passive heatsinks, AEROFIN delivers improved thermal performance through controlled airflow and optimized fin design. It maintains stability during gaming, benchmarking, and content creation tasks. Suitable for system integrators, DIY builders, and overclockers, it supports high-performance NVMe drives in compact and custom builds.

ARES AEROFIN provides efficient, reliable cooling for PCIe Gen5x4 SSDs, helping reduce overheating, maintain consistent high-speed performance, and enhance overall system performance with cooler, faster storage.

**DATOTEK INTERNATIONAL CO., LTD.**
- www.datos.com.tw
- **I1124** | TaiNEX 1

# DATO Magnetic External SSD Wins 2026 Taiwan Excellence Award

## High-Speed USB4 & Magnetic Portable SSD Solutions for Creators and Professionals

DATO announced its Q4+ and QUANTUM magnetic portable SSDs, both winners of the Taiwan Excellence Award 2026, showcasing advanced external solid-state drive solutions for creators and professionals.

The Q4+ is a powerful USB4 external SSD, reaching up to 4,000MB/s read and 3,600MB/s write speeds, with up to 4TB capacity. Its magnetic modular design and integrated 1/4"" mount make it an ideal SSD for video production, photography, and content creators, supporting seamless camera attachment and real-time recording.

QUANTUM features dual USB Type-C ports for simultaneous data transfer and charging, with speeds up to 1,600MB/s. This high-speed portable SSD supports broad compatibility across Android, iOS, iPad Pro, Sony Alpha series, Steam Deck, and MacBook, delivering true plug-and-play usability. Positioned as a "portable creative hub," it enables flexible workflows through modular accessories for filming, streaming, and mobile work.


Both models are plug-and-play compatible across major devices and emphasize sustainability with recyclable aluminum enclosures, eco-friendly packaging, low-power design, and ISO 14064 carbon audits—aligned with global ESG and green technology standards.

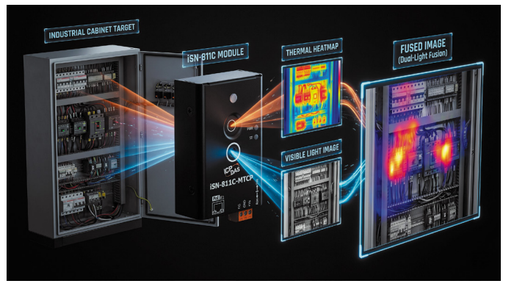




# ICP DAS IRT Series Enhances Power Distribution and Equipment Safety with Infrared Thermal Monitoring

## Image Fusion and Alarm Management for Predictive Maintenance

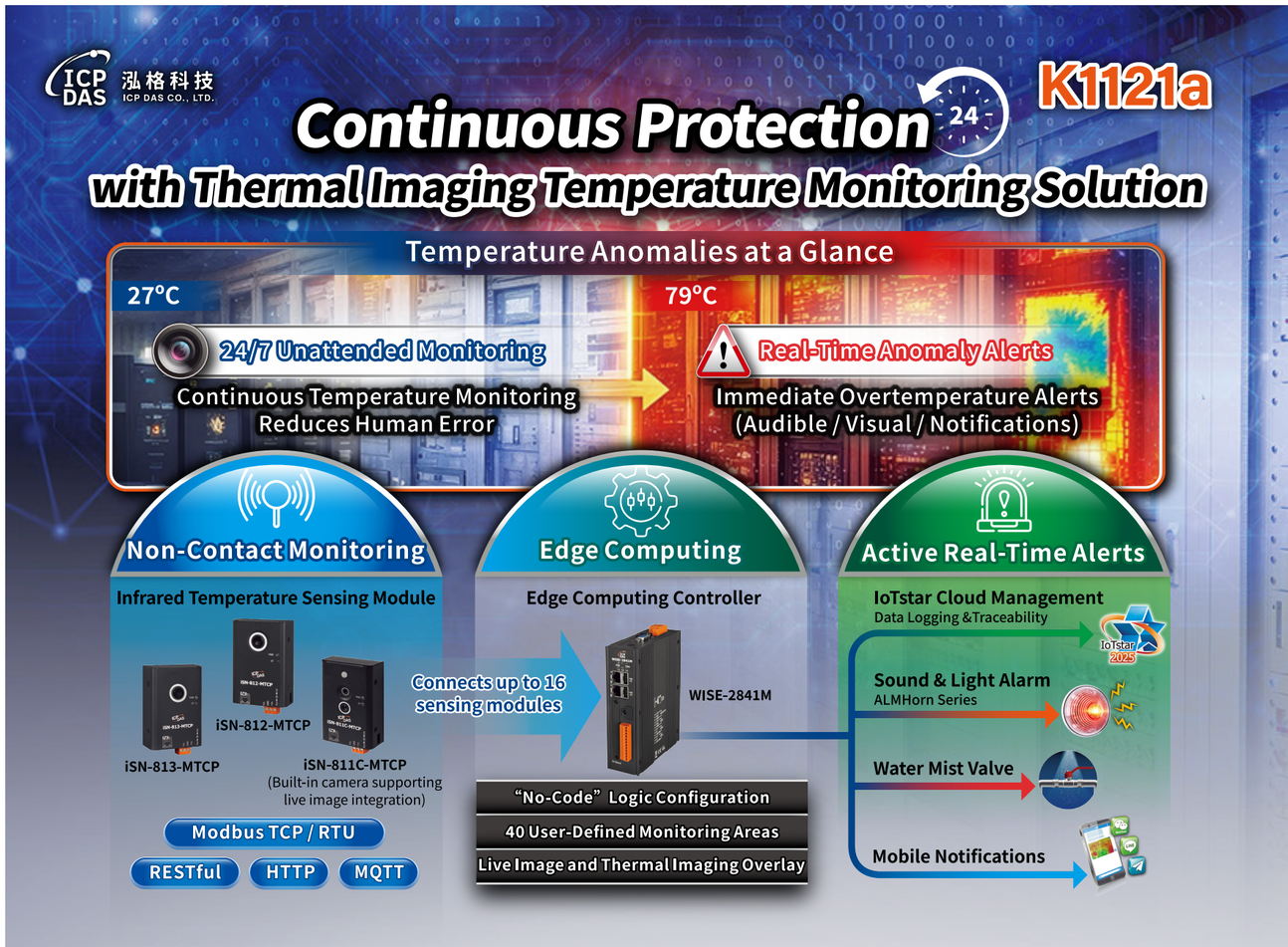
As industrial sites place increasing demands on safety and operational stability, ICP DAS introduces the IRT Series thermal imaging monitoring solution to help enterprises strengthen equipment health monitoring and predictive maintenance capabilities. Through non-contact thermal imaging technology, the system can monitor temperature changes in distribution panels, busbars, and critical equipment in real time, enabling early detection of abnormal hotspots and effectively reducing the risk of unplanned downtime.




The IRT Series supports thermal and visible-light image fusion technology, providing intuitive temperature distribution visualization and precise hotspot positioning. It also features multi-region (ROI) monitoring and alarm threshold configuration, enabling wide-area monitoring while maintaining accurate localized temperature measurement. In addition, the system offers flexible scalability and a web-based interface to enhance deployment efficiency and offer greater convenience in remote management.

For communication integration, the IRT Series supports Modbus RTU/TCP, MQTT, and RESTful API, enabling seamless connectivity with SCADA and IIoT platforms. The solution is ideal for power systems, EV charging infrastructure, and various industrial environments, helping enterprises build safer, more efficient, and predictive smart monitoring systems.

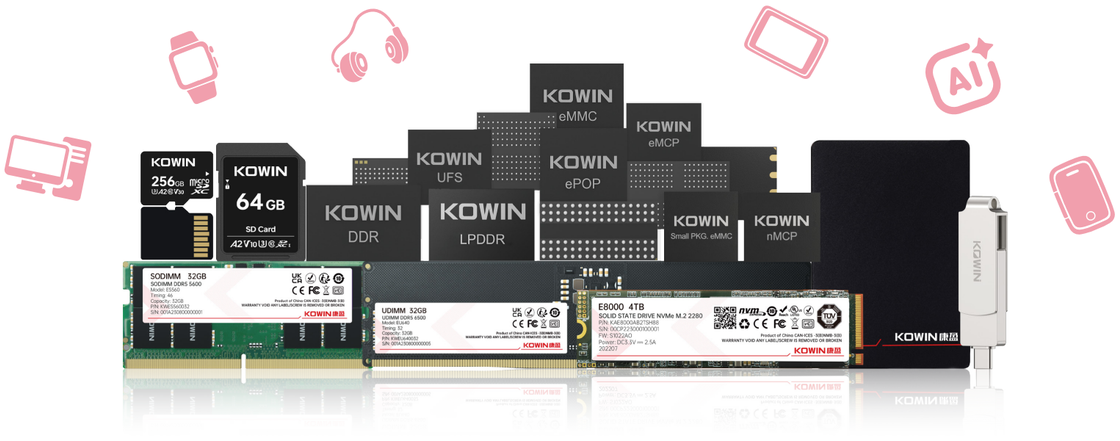
**ICP DAS CO., LTD.**
- www.icpdas.com
- **K1121a** | TaiNEX 1



# KOWIN TECHNOLOGY CO.,LTD

Ultra-reliable and Innovative Storage Solution Provider

**Booth No.: Q0924, 1F, TaiNEX 2**




## About KOWIN

KOWIN Technology Co., Ltd specializes in the research, design, and sales of embedded storage, mobile storage, memory module, solid state drive. Products include **eMMC, Small PKG. eMMC, eMCP, ePOP,nMCP, UFS, DDR, LPDDR, SSD, Memory Card, Memory Module, USB Flash Drive** etc. These products are widely used in smart terminals, smart home devices, smart wearables, IoT, IVI, network communication devices, industrial control equipments, smart health care and other applications.

| | | | | |
|---|---|---|---|---|
| **Product Category** | eMMC | Small PKG.eMMC | UFS | ePOP |
| | eMCP | nMCP | DDR | LPDDR |
| | SSD | Memory Module | Memory Card | USB Flash Drive |

KOWIN

www.kowin.com.cn

Grounded in Top-quality, Driven by New Technology

# Eugene Electric: Next-Gen Immersion Cooling for Hyperscale Computing

## Empowering High-Density AI with Modular Two-Phase Blade and Advanced Single-Phase Solutions

As the global demand for next-generation AI infrastructure and extreme-TDP processor architectures continues to accelerate, traditional cooling reaches its physical limits. Eugene Electric addresses this challenge by providing a complete, high-density cooling infrastructure that ensures unprecedented efficiency and reliability. At InnoVEX 2026, Eugene introduces its latest integrated immersion cooling portfolio, designed to empower AI supercomputers with a seamless path from single-phase reliability to extreme phase-change performance.

### Redefining Density with Modular Two-Phase Blade Immersion Cooling

For hyperscale AI training where power density exceeds 120kW per rack, Eugene's Modular Two-Phase Blade Immersion Cooling System sets a new industry standard. This advanced technology leverages latent heat transfer to achieve a market-leading mPUE of 1.01, effectively doubling the cooling capacity of traditional Direct Liquid Cooling (DLC) systems. The modular design allows data center operators to scale up to 240kW per rack, increasing space utilization by over 200%. Paired with our high-efficiency Coolant Distribution Units (CDU), this system creates a closed-loop environment that maximizes heat recovery and operational savings, delivering a projected 10-year TCO reduction of over $220 million for a 50MW-scale installation.


Modular Two-Phase Blade Immersion Cooling System, utilizing phase-change technology for high-density server cooling.

### Ensuring Operational Reliability with Single-Phase Immersion Cooling

Eugene's 28U Single-Phase Immersion Tank serves as a robust foundation for edge computing and high-density AI nodes. Engineered with a specialized 304 stainless steel tank and IP67-rated sealing, this solution provides a stable environment for mission-critical hardware. By utilizing high-performance dielectric fluorinated fluids, known for their exceptional dielectric strength and environmental sustainability (low GWP), the system achieves consistent thermal stability. This single-phase architecture ensures a simplified maintenance cycle while supporting up to 40kW of cooling capacity, making it the premier choice for enterprises seeking immediate liquid-cooled scalability.


Single-Phase Immersion Cooling Tank, utilizing dielectric immersion technology for reliable and fanless thermal management.

### Optimizing System Synergy with High-Precision Cooling Ecosystem

A high-performance system is only as strong as its components. Eugene's ecosystem features NVIDIA RVL3.0 certified UQD/MQD connectors, ensuring seamless integration with premier AI hardware while utilizing non-drip technology to guarantee hardware safety during hot-swapping. To ensure absolute reliability, our solutions utilize advanced fluorinated cooling fluids. These non-conductive, non-flammable media feature exceptional dielectric strength, high chemical stability, and zero residue. With zero ODP and low GWP for global sustainability, this integrated approach ensures that next-generation AI workloads—from LLM training to inference—operate at peak efficiency with zero downtime.

Non-Drip Quick Disconnect Couplings, featuring high-flow and leak-free design for reliable liquid cooling connectivity.

### Your Premier Partner in the AI Liquid Cooling Revolution

Eugene Electric is more than a hardware provider; the company is a total solution partner. This comprehensive suite of immersion technologies and precision components provides the sustainable, cutting-edge foundation required to accelerate AI innovation. From single-rack deployments to multi-megawatt clusters, Eugene's solutions are validated for the most demanding environments of tomorrow.

**EUGENE ELECTRIC CO., LTD. (EXHIBITED BY LIN XIAO INVESTMENT CO., LTD.)**

- www.eugene-elec.com.tw
- **S0117** | TaiNEX 2

# Advanced Data Capture Through Integrated RFID and Barcode Technology

## 36 Years of Engineering Excellence in AIDC Solutions, from Design, Manufacturing to Global Deployment

For 36 years, Marson Technology has been deeply rooted in Taiwan, specializing in the research, development, and manufacturing of advanced equipment for Industrial IoT and AIDC applications. With extensive OEM/ODM experience, we focus on delivering flexible, high-quality solutions that help businesses improve efficiency, accuracy, and scalability in an increasingly connected world.

At this year's tradeshow, we are proud to introduce our latest Industrial RFID 2D Barcode Dual-Mode Scanner. Designed for mobile operations and smart environments, this solution enables real-time data capture and seamless transmission to IoT platforms. By integrating identification, tracking, and connectivity into one efficient tool, it empowers businesses to accelerate digital transformation & achieve smarter, data-driven operations.



**MT859UHF UHF / 2D Barcode Reader**

This versatile device integrates UHF RFID and 2D barcode scanning into a single compact solution. With Bluetooth® 5.0 and USB connectivity, users can easily switch between scanning modes depending on operational needs, from inventory management to shipment verification. Its lightweight 87.3g design enhances mobility, while IP55 protection and 1.5-meter drop resistance ensure durability. The antimicrobial housing also makes it suitable for healthcare environments requiring frequent cleaning.


**MR13 UHF 2D Handheld Scanner**

MR13 delivers exceptional flexibility with both wireless and wired connectivity options. Supporting global UHF frequency bands across the US, EU, and Japan, it is ideal for international deployment. With reading distances up to 110 cm for UHF tags and 690 mm for barcodes, it ensures reliable performance across diverse applications. Notably, when paired with its optional charging base, the Bluetooth communication range can be extended up to 60 meters, making it especially effective for large warehouses and wide operational areas. Its ergonomic design, responsive trigger, and durable construction further enhance usability in demanding environments.

**MT588 2D Wearable Ring Scanner**

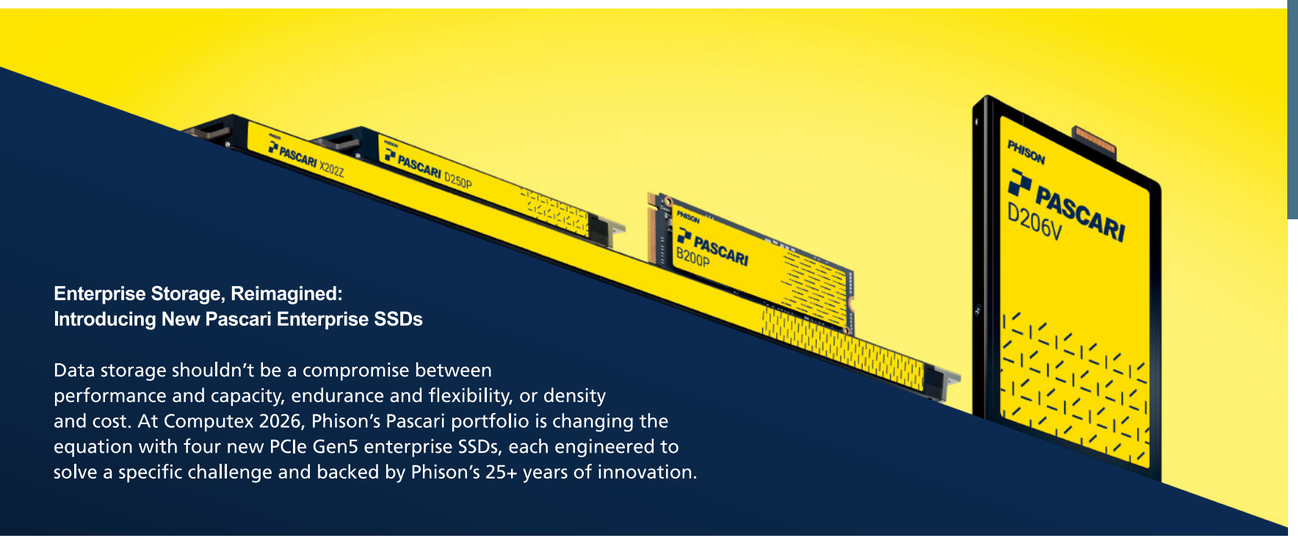
Designed for hands-free efficiency, MT588 wearable scanner enables users to work faster and more comfortably in high-volume operations. Its ultra-lightweight design minimizes fatigue, while the megapixel sensor ensures fast and accurate barcode capture. The dual touch-trigger design enhances usability without compromising comfort. With antimicrobial protection and disinfectant-ready materials, it is especially suitable for healthcare and hygiene-sensitive environments.

**MARSON TECHNOLOGY CO., LTD.**

- www.marsonscan.com
- **P1219** I TaiNEX 2

PHISON
PASCARI

# New, and Already in a Class of Its Own




**Enterprise Storage, Reimagined:**
**Introducing New Pascari Enterprise SSDs**

Data storage shouldn't be a compromise between performance and capacity, endurance and flexibility, or density and cost. At Computex 2026, Phison's Pascari portfolio is changing the equation with four new PCIe Gen5 enterprise SSDs, each engineered to solve a specific challenge and backed by Phison's 25+ years of innovation.


### Pascari X202Z: Relentless performance. Built to endure.

When workloads never let up, your storage can't either. The Pascari X202Z enterprise SSD is engineered for write-intensive environments, delivering sustained PCIe Gen5 performance with extreme endurance to keep mission-critical operations running without interruption.

### Pascari D206V: More capacity. Less compromise.

Data keeps growing. Budgets don't. The Pascari D206V PCIe Gen5 data center SSD packs massive capacity into a single drive, helping you store more, scale faster, and reduce footprint and power — with up to an 8-to-1 capacity advantage over traditional hard drives to dramatically cut OPEX.

### Pascari D250P: Next-generation performance, built for modern deployment.

Built for modern data center environments, the Pascari D250P expands the Pascari portfolio with an enterprise SSD that brings together performance, flexibility, and enterprise-grade protection for today's infrastructure.

### Pascari B200P: Boot faster. Do more.

Modern platforms demand more from their boot drives. The Pascari B200P enterprise boot drive delivers PCIe Gen5 speed in a compact M.2 2280 form factor for fast startup, reliable performance, and enterprise-grade protection without sacrificing space.

**Explore the Complete Pascari Enterprise SSD Lineup:**
**One portfolio. Support for every workload.**

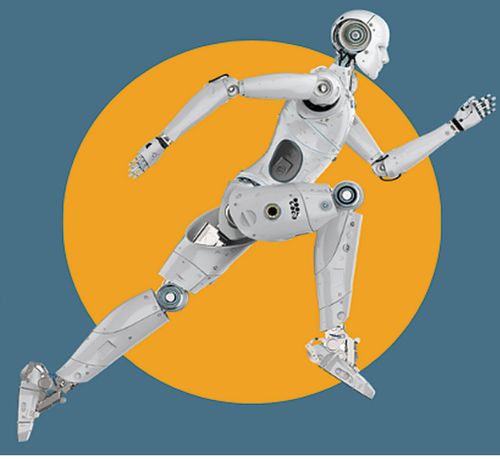
From performance to capacity to endurance, Pascari SSDs are built on Phison's in-house controller technology and deep NAND expertise. Backed by global infrastructure and a 5-year limited warranty, the Pascari portfolio is built to support every workload without compromise.

*Warranty, support, and regulatory information available at phisonenterprise.com. Product specifications subject to change without notice. Phison, the Phison logo, Pascari, and the Pascari logo are registered trademarks or trademarks of Phison Electronics Corp. or its affiliates.*





# 人形機器人 測試驗證服務



# Humanoid Robot Testing & Certification

| | Project | Standard | Application |
|---|---|---|---|
| **Electrical Safety** | IEC 62368-1 / IEC 60204-1 | audio-visual and information communication equipment / mechanical equipment | worldwide |
| | UL 62368 | Electrical safety of audio-visual and information communication equipment | |
| | CE-LVD | EU Low Voltage Directive | EU |
| | IEC 62133 / UN 38.3 | Lithium battery safety / transportation safety | worldwide |
| **EMC** | CE EMC Directive | EN 55032, EN 55035, EN 61000-4 , EN61000-6 | EU |
| | FCC Part 15 Sub-B | Radiated interference, conducted interference | |
| | KC EMC | KCC Verification | South Korea |
| **Wireless Verification** | CE RED Directive | EN 300, 328 , etc. | EU |
| | FCC ID | Wireless communication device verification | |
| | TELEC / SRRC / KC | Wireless device type verification | Japan. China. Korea |
| | Bluetooth SIG verification | Bluetooth device compatibility | Worldwide |
| **Mechanical Safety and Functional Safety** | ISO 12100 | Mechanical Safety Design Guidelines | All apps |
| | ISO 13849 / IEC 62061 | Functional safety performance level | Industrial use |
| | ISO 10218-1/2 | Industrial robots | factory |
| | ISO/TS 15066 | Collaborative ( including humanoid ) robots | Human-machine collaboration |
| | Regulation (EU) 2023/1230 | EU Machinery Regulations | EU |
| **Software and Cyber-security** | ISO/IEC 27001 | Information security management -Cloud-based functions / human-computer interaction | EU |
| | ISO/IEC 62443 | Industrial cybersecurity | Industrial robots |
| | EN 18031 | EU Radio Security | EU |
| | NIST CSF | US cybersecurity framework | US |
| | GDPR , CCPA | EU Personal Data Protection Act, California Consumer Privacy Act | Europe / USA |
| **Product design and reliability verification** | HALT/HAS Procedures, FMEA/DFMEA , IEC 62506 , MIL-HDBK-217/ Telecordia SR332 | Accelerated life testing, failure mode and effect analysis / accelerated life testing / reliability prediction | Product Design Validation |
| | MIL-STD-810 , IEC 60721-3 , IEC 60068-2 , IEC 60529, EIA-364 / IPC-A-610/ IPC TM-650 | Environmental engineering, environmental conditions, environmental testing methods, dustproof / waterproof testing | Reliability verification |
| | ASTM D4169/ ISTA series | Packaging and transport testing | US / EU |
| **Human contact** | ISO 10993 | Material biocompatibility | Medical care |
| | CP65 | Hazardous substance restrictions | Environmental compliance |
| **Evironment Friendly** | RoHS . REACH . POPs, TSCA ODS. | Chemical testing of prohibited and restricted substances | Global compliance |
| **Other** | Medical care | FDA / MDR ( Medical Use ) | US / EU |
| | Education / Childcare | ASTM F963 , EN 71 | US / EU |
| | Ride-able | ISO 13482 | worldwide |

SGS EMC Laboratory doris-tw.wang@sgs.com
SGS Safety Laboratory karen.peng@sgs.com
SGS Wireless Lab phill.wang@sgs.com

SGS Reliability Lab curtis.fu@sgs.com
SGS Cybersecurity Lab cyber.cdtl.tw@sgs.com
SGS HardLine Leb Jeako.Lai@sgs.com

SGS

# Supermicro Introduces 3 DCBBS Components for High-Density AI Data Centers

Supermicro's Data Center Building Block Solutions® (DCBBS) provides end-to-end solutions from system to rack to data-center scale. Featuring validated server racks, coolant and cooling systems, energy storage solutions, and more, DCBBS delivers complete, modular AI infrastructure to provide end-to-end deployment flexibility. While compute systems are often the focus of a data center build-out, supporting infrastructure such as power delivery, cooling, and racks are equally important in delivering complete data center solutions.

In-row cluster shot

### Self-Contained Energy Storage Solution Optimized for Safety and Performance

Supermicro's Battery Energy Storage System (BESS) is a robust power delivery solution that is purpose-built to support mission-critical AI data centers. It is designed and manufactured with a safety-first mindset, featuring an advanced liquid-cooled, high-density design that improves energy efficiency.

BESS incorporates safe LFP cells with advanced management, multi-layer fire barriers, and clean-agent suppression for maximum safety and reliability. Peak shaving and power smoothing reduce energy costs while stabilizing fluctuating AI workloads, and a comprehensive thermal management system ensures consistent, long-lasting performance, making it ideal for demanding data center environments.


BESS

### Advanced High-Performance Coolant Engineered for High-Density Liquid Cooled AI Systems

Supermicro's SMC PG25-A coolant is a high-performance PG-based synthetic liquid designed for direct-to-chip liquid cooling in high-density AI and HPC data centers. It delivers excellent long-term thermal and chemical stability, ensuring reliable performance under continuous operation while minimizing degradation, extending service life, and reducing maintenance.

The coolant provides advanced multi-metal protection and superior anti-bacterial performance, reducing risks of corrosion, scaling, and biofouling. It offers broad compatibility with various materials, along with customizable formulations to address customers' specific requirements.

### Purpose-Built Racks Engineered for High-Density Compute and Advanced Liquid Cooling

Supermicro's in-house designed racks are engineered to support the extreme weight of fully populated GPU servers, power systems, and liquid cooling components. With reinforced chassis offering a certified static load capacity of up to 2,500kg, these racks significantly exceed industry standards for structural integrity. Built with premium materials and precision manufacturing, they deliver exceptional durability, seismic and vibration resistance (GR-63-CORE Zone 4 certified), and seamless integration with in-rack/in-row CDUs, sidecars, RDHx, and manifolds. Factory pre-assembly combined with a global production capacity of 6,000 racks per month enables rapid deployment, providing a robust, scalable foundation for next-generation liquid-cooled AI clusters.

### Build the Future of AI with Supermicro

Supermicro's DCBBS provides end-to-end deployment flexibility for every step of the AI journey – from individual systems to complete racks, site infrastructure, management software, and professional services. With Supermicro's first-to-market advantages, one-stop-shop with onsite services, workload-focused customization, and validated components, DCBBS delivers everything needed to accelerate time-to-online for liquid-cooled AI data centers.

For more information, visit the DCBBS website at: supermicro.com/dcbbs

**SUPERMICRO**

- www.supermicro.com/en/
- **N0602** | TaiNEX 1



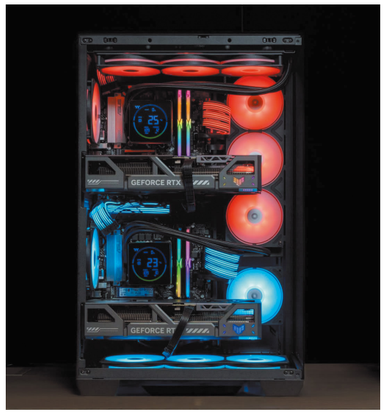


# Thermaltake Introduces the CAPO X Dual-System Chassis

Thermaltake, a leading PC DIY brand for premium hardware solutions, is redefining the concept of multi-system computing with the new CAPO X dual-system chassis. Short for Cross-platform Architecture for Parallel Operation, CAPO X is designed for users who need two fully independent PC systems within a single footprint, bringing together productivity, entertainment, and flexibility in one unified platform.

Built around a dual-system Micro-ATX architecture, CAPO X supports two complete systems operating simultaneously inside the same chassis. Whether used for AI workloads, streaming, professional applications, or shared gaming environments, CAPO X enables users to separate tasks across dedicated systems while maintaining a cleaner and more space-efficient setup.

As AI computing continues shifting from centralized infrastructure toward localized AI PCs, CAPO X provides enthusiasts and professionals with a platform built for powerful DIY AI systems. Its physically isolated dual-system design allows users to dedicate one system to AI agents, background processing, or high-security tasks, while the second system remains protected for personal or professional work. Data can be transferred securely through cloud-based workflows or direct networking without compromising system separation.




For streamers and content creators, CAPO X delivers a dedicated dual-PC streaming setup in a single chassis. One system can focus entirely on gaming performance while the second independently handles encoding, broadcasting, recording, and community management. By separating workloads, users benefit from improved stability and uninterrupted streaming performance during intensive sessions.

The chassis also caters to professional users who require multiple operating systems running simultaneously. Developers, engineers, and creators can configure separate Windows and Linux environments within the same enclosure, enabling more efficient multitasking and seamless cross-platform workflows. The systems can also be linked directly through Ethernet for streamlined data sharing and communication.

Beyond productivity, CAPO X introduces a unique solution for shared environments. Couples, roommates, or friends can maintain separate systems while sharing a single desk setup. Its vertical stacking layout occupies significantly less space than two traditional towers, while the panoramic curved tempered glass design creates a symmetrical showcase for both builds.

CAPO X combines this flexibility with extensive hardware support. The chassis supports hidden-connector motherboards, up to thirteen 120 mm fans, and dual 360 mm radiators mounted simultaneously on the top and side for optimized cooling performance. Built with durable 1 mm SPCC steel on the supporting structures, the structure is engineered to support the weight and thermal demands of two high-performance systems while maintaining a clean and modern presentation.

By merging dual-system functionality with a compact, visually unified design, CAPO X represents a new direction for users who demand both performance and versatility from their PC setup.

**THERMALTAKE**

- www.thermaltake.com
- **N0102** | TaiNEX 1

# EZCast Breaks New Ground: 4K 60Hz Wireless Display Achieving Wired-Level Low Latency


For years, wireless display technology has forced professionals into an uncomfortable trade-off: accept the freedom of wireless connectivity, or accept the performance of a wired connection, but never both. EZCast challenges that assumption at Computex 2026 with the debut of Compact Air, a professional-grade wireless display solution engineered to deliver wired-level responsiveness without sacrificing portability.

### Breaking the Resolution and Latency Barrier

As 4K resolution becomes the established standard in professional display environments, the bar for wireless display continues to rise. High-resolution output means little if the connection cannot keep pace with the demands of real-time workflows. Compact Air answers that challenge directly, supporting 4K at 60Hz for crisp, high-fidelity output and 1080p at 120Hz for applications where fluid motion is paramount, setting a new benchmark for wireless display resolution. Whether rendering complex data visualizations, delivering high-definition presentations, or supporting creative workflows that demand color accuracy and detail, Compact Air ensures the display keeps up with the work.

Equally critical is latency. Most wireless display products on the market operate at 80 to 100 milliseconds, while Compact Air pushes that boundary to below 20 milliseconds, less than the duration of a single frame on screen, a gap too brief for the human eye to detect. The result is an on-screen response free of perceptible mouse lag and micro-stuttering, meeting the demands of high-stakes conference presentations and enterprise-grade display environments where precision and reliability are non-negotiable.

### Enterprise-Ready in an Ultra-Compact Package

Performance at this level has historically come at the cost of bulk. Compact Air breaks that convention. Engineered with an ultra-compact form factor that integrates multiple chips into a single SoC, it is designed for the high-mobility professional and available in both USB-C and HDMI transmitter configurations, enabling driver-free, native integration across a broad range of laptops and tablets with no additional adapters required. Its plug-and-play design means setup takes seconds, allowing professionals to transition seamlessly between meeting rooms, client sites, and collaborative spaces without configuration overhead. Compact Air also incorporates WPA3 encryption, meeting the strict data protection requirements of enterprise environments and ensuring that sensitive information remains secure throughout every transmission.

### Raising the Industry Baseline

EZCast's broader ambition with Compact Air goes beyond a single product launch. By setting 4K at 60Hz as the new minimum standard for professional wireless display, EZCast aims to raise the bar for the entire industry, not just in specifications, but in the expectations professionals bring to every meeting room, every collaboration space, and every mobile workflow. Making high-resolution, low-latency wireless connectivity not a premium feature, but a professional necessity.

**WINNER WAVE TW LIMITED (EZCAST)**

- www.ezcast.com
- **Q0634c** | TaiNEX 2





# AI-Native SaaS Platform for Growth Enterprises and Intelligent Global Operations

YonSuite is Yonyou's AI-native SaaS platform designed for growth enterprises entering a new stage of digital and intelligent transformation. Built on a dual cloud-native and AI-native architecture, YonSuite brings applications, data, intelligence, integration, and development capabilities into one unified platform, helping companies manage business expansion with greater speed, visibility, and control.

Covering finance, tax, HR, supply chain, marketing, procurement, manufacturing, R&D, projects, assets, and collaboration, YonSuite supports end-to-end operations across the full enterprise value chain. Its "One AI-World, One YonSuite" concept connects global operations, integrated business scenarios, a unified work portal, intelligent platform capabilities, ecosystem integration, and AI-driven customer success into a practical operating model for growing companies.

With AI embedded into core scenarios, YonSuite enables intelligent accounting, business analysis, HR management, procurement, inventory, retail, quality inspection, and collaboration assistants. Enterprises can move from fragmented tools and delayed reports toward real-time insights, process automation, and more accurate decision-making across daily operations, while keeping teams aligned through a single digital workspace.

For companies operating across regions, YonSuite supports multi-language, multi-currency, multi-time-zone, multi-accounting-standard, and multi-data-center requirements. It also provides global finance and tax, HR, supply chain, procurement, manufacturing, R&D, project, asset, and collaborative office capabilities, helping enterprises coordinate headquarters and overseas entities within a consistent management framework.

At COMPUTEX, YonSuite presents a practical path for growth enterprises to adopt enterprise AI, connect global operations, and build a more agile, intelligent, and scalable business system.

For more information, please visit the Booth at the exhibition.

**YONYOU TAIWAN CO., LTD.**

- www.yonyou.com.tw
- **R0325a** | TaiNEX 2

**BOOTH PRESENTATION 攤位演講**

**14:00 / DAILY** | **R0325a / Hall2 4F**

## YonSuite AI + Full Scenarios Empowering Smart Enterprises

One AI-World

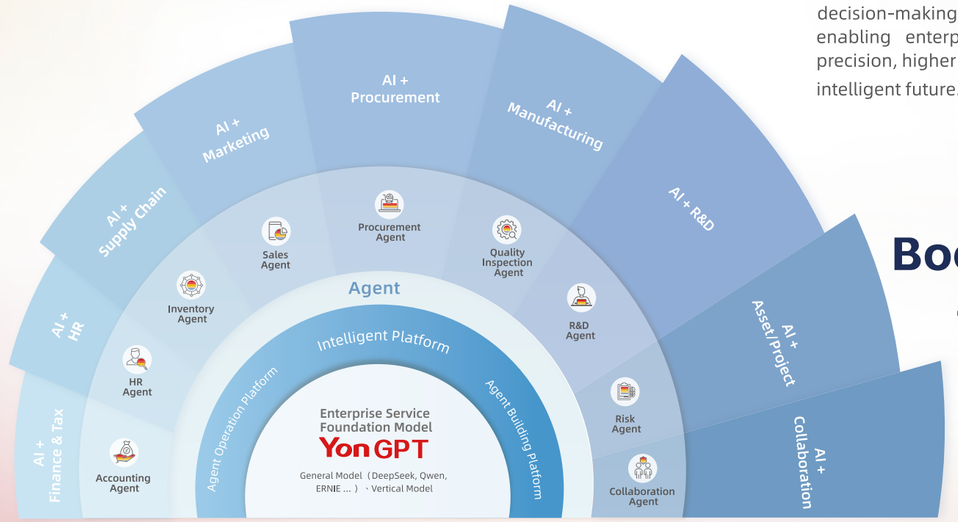
OneYonSuite

**1,600+** Overseas Clients | **40+** Countries and Regions

yonyou

### Deep Enablement

YonSuite drives profound digital transformation through its integrated "AI + Full-Scenario" approach. By combining advanced AI capabilities with industry expertise, it delivers intelligent support across every business function. YonSuite redefines decision-making with data-driven insights, enabling enterprises to achieve greater precision, higher effciency, and a path to an intelligent future.




**Booth R0325a**
**4F,Hall2**

ADVANTECH

*Enabling an Intelligent Planet*

COMPUTEX TAIPEI

## *Edge Computing & AI-Powered WISE Solutions*


# Advantech at COMPUTEX 2026

### Advantech Brand Pavilion

**June 2 - 5** TaiNEX 1, 1F, Booth #K0603a 09:30 – 17:30

Catch a glimpse of what awaits at the Advantech Brand Pavilion. Discover how Edge Computing and AI-powered WISE solutions are transforming industries through platforms, software, and intelligent systems. From robotics and automation to healthcare, retail, and hospitality, experience real-world applications through live demos and visionary insights.

Visit Advantech Booth at COMPUTEX

## Edge AI & Robotics Platform

As an Edge AI enabler, Advantech provides essential building blocks for Edge AI and Physical AI, from AI-on-Modules and AI appliance systems to HPC systems, integrated with software platforms and design-in services to accelerate real-world AI adoption across industries.

- Leading Edge AI Platforms: Powered by NVIDIA, Qualcomm, Intel, and AMD
- Physical AI Robotics Building Blocks: Computing, Sensor fusion, Software Solution, and Ecosystem
- Edge Value Solutions: Pre-qualified, co-designed hardware-software for accelerated time-to-market
- Real-World Applications: Gen AI, Vision AI, and Humanoid Robotics

## Edge AI Software Platform

WISE is Advantech's core engine for Industrial AI, integrating high-performance servers, the WEDA developer architecture, and WISE-IoT domain solutions to power the full industrial AI lifecycle.

Witness the power of the WISE Ecosystem:

- Up to 86% faster Edge AI development
- Digital twins with Nvidia Omniverse
- Domain AI Agents entering real operational workflows
- Software-defined Hardware and solutions

## Industrial Automation & Intelligent Systems

Advantech's Industrial Automation & Intelligent Systems provide rugged edge AI and IoT solutions to optimize iFactory operations, elevate iEquipment, and ensure highly reliable performance across the Energy & Utilities and Transportation sectors.

See our solutions in action:

- Manufacturing: Next-gen iFactory & AI-powered iEquipment
- Energy & Utilities: Resilient operations with sustainable intelligence
- Transportation: Safer, faster, and more efficient mobility

## iHealthcare, iRetail and Hospitality

Advantech empowers healthcare and retail innovation through Edge AI and modular platforms, delivering real-time insights that optimize operations, strengthen decision-making, and enable more responsive service experiences.

Explore the intelligence behind the modern city:

- Intelligent healthcare technology empowering better care
- Frictionless retail customer journey with AI-powered services
- Integrated edge intelligence driving real-time insights

MiTAC Computing

# Defining Sustainable AI Infrastructure

R0504, 4F, Hall 2

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Event Page

* While supplies last. 數量有限，送完為止。